

CLAIMS

What is claimed is:

- 5 1. A circuit, comprising:
 electronic component;
 structure for reducing thermal drift in the
electronic component.
- 10 2. The circuit of claim 1, wherein the structure
comprises a material that increases a thermal mass of
the electronic component.
- 15 3. The circuit of claim 2, wherein the material
comprises a metal case around the electronic
component.
- 20 4. The circuit of claim 2, wherein the material
comprises a ceramic case around the electronic
component.
5. The circuit of claim 1, wherein the structure
comprises an insulator.
- 25 6. The circuit of claim 1, wherein the structure
comprises a material that increases a thermal mass of
the electronic component and an insulator that
encases the electronic component and the material.
- 30 7. The circuit of claim 1, wherein the structure
comprises a circuit board that holds the electronic
component which is separated from a circuit board
that holds a set of other components of the circuit.

8. The circuit of claim 7, wherein the structure further comprises a material that increases a thermal mass of the electronic component.

5 9. The circuit of claim 7, wherein the structure further comprises an insulator over the electronic component.

10 10. The circuit of claim 7, wherein the structure further comprises a material that increases a thermal mass of the electronic component and an insulator that encases the electronic component and the material.

11 11. The circuit of claim 1, wherein the structure comprises a gap which reduces a heat conduction path a ground plane in a circuit board and the electronic component.

20 12. The circuit of claim 1, wherein the circuit is an oscillator circuit.

13. The circuit of claim 1, wherein the circuit is a clock circuit.

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14. The circuit of claim 12, further comprising:
means for communication via a network;
means for synchronizing a local time value in
the clock circuit in response to a set of messages
30 transferred via the network.

15. A distributed system having a set of nodes, each node comprising:

local clock including a crystal component;
structure for reducing thermal drift in the
electronic component.

5 16. The distributed system of claim 15, wherein the
structure comprises a material that increases a
thermal mass of the electronic component.

10 17. The distributed system of claim 16, wherein the
material comprises a metal case around the electronic
component.

15 18. The distributed system of claim 16, wherein the
material comprises a ceramic case around the
electronic component.

19. The distributed system of claim 15, wherein the
structure comprises an insulator.

20 20. The distributed system of claim 15, wherein the
structure comprises a material that increases a
thermal mass of the electronic component and an
insulator that encases the electronic component and
the material.

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